

**In The Title:**

Please amend the title as follows:

-- INTERCONNECT STRUCTURE ~~WITH AN ENLARGED AIR GAPS DISPOSED~~  
~~BETWEEN CONDUCTIVE STRUCTURES OR SURROUNDING A CONDUCTIVE~~  
~~STRUCTURE WITHIN THE SAME~~--

**In The Specification:**

Paragraph beginning at line 4 of page 1 has been amended as follows:

--[This application is a continuation-in-part of prior application Ser. No. 09/389,823, filed Sep. 3, 1999 and Ser. No. 09/545,651, filed Apr. 10, 2000.]~~This application is a divisional application of, and claims the priority benefit of, U.S. application serial No. 09/971,471, filed October 05, 2001, which is a continuation-in-part of applications serial No. 09/389,823, filed September 3, 1999, now granted as U.S. patent No.6,077,767, and serial No. 09/545,651, filed April 10, 2000, now abandoned.~~--